
APPENDIX V

STATUTORY AND GENERAL INFORMATION

A. FURTHER INFORMATION ABOUT OUR COMPANY AND OUR SUBSIDIARIES

1. Incorporation

Our Company was established as a limited liability company in the PRC on August 26, 2019 and was converted into a joint stock limited company on May 18, 2026 under the laws of the PRC. As of the Latest Practicable Date, the registered share capital of the Company was RMB846,544,528.

Our Company has established a place of business in Hong Kong at 40th Floor, Dah Sing Financial Center, 248 Queen’s Road East, Wan Chai, Hong Kong. Our Company has been registered as a non-Hong Kong company in Hong Kong under Part 16 of the Companies Ordinance on [●] with the Registrar of Companies in Hong Kong. Ms. Lam Wai Yee Sophie (林慧怡) has been appointed as authorized representative of our Company for the acceptance of service of process and notices on behalf of our Company in Hong Kong. The address for service of process is the same as our Company’s principal place of business in Hong Kong as set out above.

As we are established in the PRC, our corporate structure and Articles of Association are subject to the relevant laws and regulations of the PRC. A summary of the relevant provisions of our Articles of Association is set out in “Appendix IV — Summary of Articles of Association”.

2. Changes in Share Capital of Our Company

On July 30, 2025, the registered share capital of our Company was decreased from US\$178,464,543 to US\$110,131,210.

The registered capital of our Company was changed from US\$110,131,210 to RMB737,655,639 upon completion of the joint stock reform of our Company on May 18, 2026. As of the date of our establishment as a joint stock company with limited liability, our registered capital was RMB737,655,639 consisting of 737,655,639 issued Shares with a nominal value of RMB1.00 each, which has been fully paid up by our promoters.

The registered capital of our Company was increased from RMB737,655,639 to RMB846,544,528 consisting of 846,544,528 issued Shares on May 18, 2026.

Save as disclosed above, there has been no alteration in the share capital of the Company within two years immediately preceding the date of this Document.

3. Changes in Share Capital of Our Subsidiaries

A summary of the corporate information and the particulars of our subsidiaries are set out in Note 24 to the Accountant’s Report as set out in Appendix I to this Document.

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Save as disclosed below and in the Accountant’s Report set out in Appendix I to this Document, there has been no alteration in the share capital of any of the subsidiaries of our Company within the two years immediately preceding the date of this Document.

<u>Name of subsidiary</u>	<u>Date of Change</u>	<u>Share capital before change</u>	<u>Share capital after change</u>
Leading Qinhuangdao	June 8, 2026	RMB500,000,000	RMB850,000,000

4. Resolutions of our Shareholders

At the general meetings of the Shareholders held on June 25, 2026, the following resolutions, among other things, our Shareholders resolved to approve the following:

- (a) the [REDACTED] by our Company of H Shares with a nominal value of RMB1.00 each and such H Shares be [REDACTED] on the Stock Exchange;
- (b) the number of H Shares to be [REDACTED] before the exercise of the [REDACTED] shall not be more than [REDACTED]% of the total issued share capital of our Company as enlarged by the [REDACTED], and granting the [REDACTED] the [REDACTED] of no more than [REDACTED]% of the number of H Shares [REDACTED] pursuant to the [REDACTED];
- (c) authorization of the Board or its authorized individual to handle matters relating to, among other things, the [REDACTED], the [REDACTED] and [REDACTED] of the H Shares; and
- (d) subject to the completion of the [REDACTED], the conditional adoption of the Articles of Association, which shall become effective on the [REDACTED] and the authorization of the Board to amend the Articles of Association in accordance with relevant laws and regulations and upon the request from the Stock Exchange and relevant PRC regulatory authorities.

B. FURTHER INFORMATION ABOUT OUR BUSINESS

1. Summary of Material Contracts

We have entered into the following contract(s) (not being contracts entered into in the ordinary course of business) within the two years immediately preceding the date of this Document that are or may be material:

- (a) the [REDACTED].

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2. Intellectual Property Rights

(a) Trademarks

As of the Latest Practicable Date, we had registered the following trademarks which we consider to be or may be material to our business:

No.	Trademark	Place of registration	Registered Owner	Class	Registration number	Registration date
1.		PRC	Our Company	40	52150888	2021-08-28
2.		PRC	Our Company	9	52145776	2021-08-28
3.		Chinese Taiwan	Our Company	9	2168403	2021-09-16
4.		Chinese Taiwan	Our Company	40	2170482	2021-09-16
5.		United States	Our Company	9	6748122	2022-05-31
6.		Chinese Taiwan	Our Company	9	2168402	2021-09-16
7.		Chinese Taiwan	Our Company	40	2170481	2021-09-16
8.		United States	Our Company	9	6840344	2022-09-06
9.		Chinese Taiwan	Our Company	9	2510463	2026-02-01
10.		Chinese Taiwan	Our Company	9	2510462	2026-02-01
11.		Chinese Taiwan	Our Company	9	2510448	2026-02-01

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As of the Latest Practicable Date, we had applied for the registration of the following trademarks which we consider to be or may be material to our business:

No.	Trademark	Place of application	Application	Class	Application number	Application date
1.		PRC	Our Company	9	88770580	2025-11-24
2.		Chinese Taiwan	Our Company	9	114086381	2025-11-24
3.		Hong Kong	Our Company	9	307197841	2026-02-24
4.		Hong Kong	Our Company	9	307199641	2026-02-26
5.		Hong Kong	Our Company	9	307199650	2026-02-26
6.		Hong Kong	Our Company	9	307199669	2026-02-26
7.		Hong Kong	Our Company	9	307199678	2026-02-26

(b) Copyrights

As of the Latest Practicable Date, we had registered the following software copyrights which we consider to be or may be material to our business:

No.	Copyright	Place of registration	Registration number	Registration date
1.	Foolproof Parameter Control Software for Soft Gold Wire Production Line (軟金線線體參數防呆軟體)	PRC	2025SR2530477	2025-12-30
2.	EMP System (EMP系統)	PRC	2023SR1495310	2023-11-23
3.	EAP Special Edition Software (EAP特別版軟體)	PRC	2024SR0817917	2024-06-17

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(c) *Patents*

As of the Latest Practicable Date, we had registered the following patents which we consider to be or may be material to our business:

No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
1.	Packaging Substrate and Packaging Structure (封裝基板及封裝結構). . .	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202120620741.5	2021-11-23
2.	Tank, Circulation Device, and Circulation System (槽體、迴圈裝置及循環系統).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221579308.2	2022-11-15
3.	Heating Plate Assembly (加熱板組件).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221527157.6	2022-12-09
4.	Packaging Structure (封裝結構).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221416390.7	2022-12-13
5.	Solder Printing Structure (焊料印刷結構).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221331155.X	2022-12-13
6.	Lamination Assembly and Lamination Apparatus (壓合元件及壓合裝置). . .	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221526175.2	2022-12-13
7.	Circuit Board Assembly (電路板元件).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221650311.9	2022-12-13
8.	Regeneration System (再生系統).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202221893658.6	2022-12-20
9.	Circuit Board and Electronic Device (電路板以 及電子裝置).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202222151385.4	2023-02-21
10.	Ball Grid Array Ball Mounting Machine (球柵陣列植球機).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202222503454.3	2023-03-17
11.	Printed Circuit Board Lamination Apparatus (印刷電路板壓合裝置). . .	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202222562310.5	2023-03-17
12.	Packaging Substrate (封裝基板).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202222529916.9	2023-04-14

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No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
13.	Hanging Basket for Easy Liquid Drainage (便於排液的掛籃).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202321230222.3	2023-10-10
14.	Suction Cup, Adsorption Mechanism, and Exposure Equipment (吸盤、吸附機構及曝光設備).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202320968934.9	2023-11-10
15.	Shield Plate (遮板).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202321693142.1	2023-12-08
16.	Conveying Device (傳送裝置).	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202322006402.X	2024-02-02
17.	Circuit Board with Embedded Components and Manufacturing Method Thereof (具有內埋元件的電路板及其製作方法). . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201310204368.5	2017-08-11
18.	Packaging Substrate and Manufacturing Method Thereof (封裝基板及其製作方法).	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210561911.2	2017-10-27
19.	Chip Packaging Structure, Circuit Board with Embedded Components, and Manufacturing Method Thereof (晶片封裝結構、具有內埋元件的電路板及其製作方法). . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210577545.X	2017-01-11
20.	Circuit Board and Manufacturing Method Thereof (電路板及其製作方法).	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201310270638.2	2017-10-27
21.	Circuit Board with Embedded Components and Manufacturing Method Thereof (具有內埋元件的電路板及其製作方法). . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210561907.6	2017-05-31
22.	IC Substrate, Semiconductor Device Having the Same, and Manufacturing Method Thereof (IC載板、具有該IC載板的半導體器件及製作方法).	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201310357713.9	2017-06-23
23.	Circuit Board and Manufacturing Method Thereof (電路板及其製作方法).	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210363035.2	2017-03-01

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No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
24.	Coreless Packaging Structure and Manufacturing Method Thereof (無芯層封裝結構及其製造方法) . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201310294203.1	2017-05-24
25.	Interconnection Substrate and Layered Packaging Structure (連接基板及層迭封裝結構)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210415956.9	2016-12-21
26.	Circuit Board and Manufacturing Method Thereof (電路板及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210502222.4	2017-03-01
27.	Coreless Packaging Substrate and Manufacturing Method Thereof (無芯層封裝基板及其製作方法) . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201310265770.4	2017-08-25
28.	Interconnection Substrate and Layered Packaging Structure (連接基板及層迭封裝結構)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210379202.2	2016-08-24
29.	Chip Packaging Substrate and Structure and Manufacturing Method Thereof (晶片封裝基板和結構及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201210360263.4	2016-11-09
30.	Circuit Board and Manufacturing Method Thereof (電路板及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201410569679.6	2019-01-25
31.	Heat Sink and Manufacturing Method Thereof and Electronic Device (散熱片及其製作方法及電子設備)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201510351996.5	2019-04-16
32.	Packaging Structure and Manufacturing Method Thereof (封裝結構及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	PRC	ZL201610255094.6	2020-05-19
33.	Packaging Substrate and Manufacturing Method Thereof (封裝基板及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd.	PRC	ZL201811240361.8	2021-10-19
34.	Circuit Board, Circuit Board Assembly, and Electronic Device (電路板、電路板元件以及電子裝置)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202120599782.0	2021-11-23

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No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
35.	Apparatus for Manufacturing IC Substrate and IC Substrate (IC載板的製備裝置及IC載板)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202120812983.4	2022-04-01
36.	Fixture (掛具)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202220671857.6	2022-09-16
37.	Ultrasonic Cleaning Apparatus (超聲波清潔裝置)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202220666658.6	2022-09-16
38.	Circuit Board (電路板)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202220633788.X	2022-11-29
39.	Film Lamination Apparatus (膜壓裝置)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202220574473.2	2022-11-29
40.	Fixing Jig for Circuit Board Manufacturing (電路板製作用固定治具) .	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202220672152.6	2023-04-07
41.	Circuit Board and Manufacturing Method Thereof (電路板及其製作方法) . .	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL201811361685.7	2023-04-18
42.	Reflow Soldering Temperature Measurement Carrier and Device (回流焊測溫載具及回流焊測溫裝置)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202223457976.0	2023-06-09
43.	Inspection Structure (檢測結構)	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202223460082.7	2023-06-20
44.	Transmission Assembly and Transmission Structure (傳輸元件及傳輸結構) . .	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202320627247.0	2023-08-18
45.	Method for Manufacturing Circuit Board (線路板的製備方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202011338132.7	2024-03-22
46.	Feeding Mechanism and Receiving Equipment (送料機構及收料設備) . .	Utility Model	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	PRC	ZL202321853965.6	2024-03-29
47.	Packaging Structure (封裝結構)	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd.	PRC	ZL202322597067.5	2024-05-10

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No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
48.	Film Peeling Machine (撕膜機)	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202322609524.8	2024-07-02
49.	Chiplet Packaging Structure (芯粒封裝結構)	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202321961053.0	2024-08-30
50.	Water Blocking Wheel Set and Etching Apparatus (擋水輪組及蝕刻裝置) . . .	Invention Patent	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202110817946.7	2024-12-27
51.	Circuit Board Assembly and Electronic Product (電路板元件和電子產品) . .	Utility Model	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. and our Company	PRC	ZL202420783552.3	2025-01-17
52.	Testing Apparatus for Semiconductor Package (半導體封裝體的測試裝置)	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202420077044.3	2025-03-07
53.	Method for Manufacturing Circuit Board (線路板的製作方法)	Invention Patent	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202110837772.0	2025-05-27
54.	Packaged Circuit Structure and Manufacturing Method Thereof (封裝電路結構及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd. And our Company	PRC	ZL202110097582.X	2025-05-27
55.	Substrate with Fine-Pitch Conductive Bumps and Manufacturing Method Thereof (具有微間距導電凸塊的基板及其製造方法)	Invention Patent	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202311830765.3	2025-05-27
56.	Packaging Structure and Manufacturing Method Thereof (封裝結構及其製造方法)	Invention Patent	Our Company	PRC	ZL202111512130.X	2024-10-22
57.	Roller Cleaning Structure, Cleaning Apparatus, and Cleaning Method (滾輪清潔結構、清潔裝置及清潔方法)	Invention Patent	Our Company	PRC	ZL202111552707.X	2025-10-28
58.	Method for Manufacturing Fine-Line Circuit Board (細線路電路板的製作方法)	Invention Patent	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202111217605.2	2025-11-25
59.	Spray Apparatus for Packaging Substrate (封裝基板的噴淋裝置) . . .	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202422314074.4	2025-09-19
60.	Photomask and Exposure Equipment (光罩及曝光設備)	Utility Model	Our Company and Leading Interconnect Semiconductor Technology Qinquangdao Co., Ltd.	PRC	ZL202520580521.2	2026-03-26

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No.	Patent name	Type	Patentee	Place of registration	Patent number	Grant date
61.	Method for manufacturing a packaged circuit structure (Method for manufacturing a packaged circuit structure).	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	United States	US17/218556	2023-06-20
62.	Packaging Substrate, Packaging Structure, and Manufacturing Method Thereof (封裝基板、封裝結構及其製作方法).	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd.	Chinese Taiwan	TW106116320	2019-07-11
63.	Method for Manufacturing Circuit Board (線路板的製備方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	Chinese Taiwan	TW109142126	2021-12-11
64.	Packaged Circuit Structure and Manufacturing Method Thereof (封裝電路結構及其製作方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	Chinese Taiwan	TW110103733	2022-12-01
65.	Packaging substrate, method for manufacturing same, and chip packaging structure having same	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and Zhen Ding Technology Co., Ltd.	United States	US14/097251	2015-10-27
66.	Circuit Board and Manufacturing Method Thereof (線路板及其製造方法)	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	Chinese Taiwan	TW112141409	2025-04-11
67.	Chip Packaging Structure, Manufacturing Method Thereof, and Electronic Device (晶片封裝結構及其製作方法和電子設備).	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd.	Chinese Taiwan	TW112115405	2024-10-21
68.	Packaged circuit structure.	Invention Patent	Leading Interconnect Semiconductor Technology Qinhuangdao Co., Ltd. and our Company	United States	US18/123881	2025-09-16

As of the Latest Practicable Date, our intellectual property portfolio included a total of 17 Material Co-owned Patents in Chinese Mainland and the United States. See “Relationship with Our Controlling Shareholders — Non-Competition Undertaking, and — Independence from Our Controlling Shareholders — Research and Development.” as to the analysis of our rights with respect to the Material Co-owned Patents.

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3. Domain names

As of the Latest Practicable Date, we owned the following domain names which we consider to be or may be material to our business:

No.	Domain Name	Registered Owner	Registration date
1.	leadingics.com	Our Company	2022-11-21
2.	eleadingics.com.	Our Company	2022-11-21
3.	leadingics.com.cn	Our Company	2022-11-21

Save as aforesaid, as of the Latest Practicable Date, there were no other trade or service marks, patents, intellectual or industrial property rights which were material in relation to our business.

C. FURTHER INFORMATION ABOUT OUR DIRECTORS AND SUBSTANTIAL SHAREHOLDERS

1. Disclosure of interests of Directors and Chief Executive of the Company

Immediately following the completion of the [REDACTED] (assuming the [REDACTED] is not exercised), so far as our Directors are aware, none of our Directors or chief executive has any interests or short positions in our Shares, underlying Shares and debentures of our Company or its associated corporations (within the meaning of Part XV of the SFO) which will have to be notified to our Company and the Stock Exchange pursuant to Divisions 7 and 8 of Part XV of the SFO (including interests and short positions which he or she is taken or deemed to have under such provisions of the SFO) or which will be required, pursuant to Section 352 of the SFO, to be recorded in the register referred to therein, or which will be required to be notified to our Company and the Stock Exchange pursuant to the Model Code for Securities Transactions by Directors of [REDACTED] contained in the Listing Rules.

2. Disclosure of Interests of Substantial Shareholders

(a) *Interests in our Company*

For information on the persons who will, immediately following the completion of the [REDACTED], having or be deemed or taken to have interests or short positions in our Shares or underlying Shares which would be required to be disclosed to our Company and the Stock Exchange under the provisions of Divisions 2 and 3 of Part XV of the SFO, or directly or indirectly be interested in 10% or more of the nominal value of any class of share capital carrying rights to vote in all circumstances at general meetings of our Company, see the section headed “Substantial Shareholders”.

(b) *Interests of the Substantial Shareholders of Other Members of Our Group*

As of the Latest Practicable Date, our subsidiaries were all wholly owned by us and our Directors are not aware of any persons who would, immediately following the completion of the [REDACTED], be directly or indirectly interested in 10% or more of the issued voting Shares of the other members of our Group (other than our Company).

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3. Service Contracts

We have entered into a contract with each of our Directors in respect of, among other things, compliance with the relevant laws and regulations, the Articles of Association and applicable provisions on arbitration.

Save as disclosed above, we have not entered, and do not propose to enter, into any service contracts with any of our Directors in their respective capacities as Directors (other than contracts expiring or determinable by the employer within one year without any payment of compensation (other than statutory compensation)).

4. Director’s Remuneration

Save as disclosed in the section headed “Directors and Senior Management” and Note 34 to “Appendix I — Accountant’s Report” for the three years ended December 31, 2025 and for the three months ended March 31, 2026, none of our Directors received other remunerations of benefits in kind from us.

5. Disclaimers

Save as disclosed in this Document:

- (a) none of our Directors or any of the parties listed in “- E. Other Information — 4. Qualifications of Experts” below is:
 - (i) interested in our promotion, or in any assets which, within the two years immediately preceding the date of this document, have been acquired or disposed of by or leased to us, or are proposed to be acquired or disposed of by or leased to our Company;
 - (ii) materially interested in any contract or arrangement subsisting at the date of this document which is significant in relation to our business;
- (b) save in connection with the [REDACTED] and the [REDACTED], none of the parties listed in “— E. Other Information — 4. Qualifications of Experts” below:
 - (i) is interested legally or beneficially in any shares in any member of our Group; or
 - (ii) has any right (whether legally enforceable or not) to subscribe for or to nominate persons to subscribe for any securities in any member of our Group;
- (c) none of our Directors or their close associates or any shareholders of our Company who to the knowledge of our Directors owns more than 5% of our issued share capital has any interest in our top five customers or suppliers; and
- (d) none of our Directors is a director or employee of a company that has an interest in the share capital of our Company which, once the H Shares are [REDACTED] on the Stock Exchange, would have to be disclosed pursuant to Divisions 2 and 3 of Part XV of the SFO.

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D. EMPLOYEE SHARE OWNERSHIP PLAN

The following is a summary of the principal terms of the Employee Share Ownership Plan in relation to our Employee Shareholding Platforms adopted by our Company on May 12, 2026 for the purpose of attracting and retaining talents for our Group. Under the Employee Share Ownership Plan, eligible participants are entitled to equity interest in the Employee Shareholding Platforms (the “Plan Shares”). As of the Latest Practicable Date, all of the Plan Shares under the Employee Share Ownership Plan have been granted to the eligible participants. See “History, Development and Corporate Structure — Employee Shareholding Platforms” for details of the ownership structure of each Employee Shareholding Platform and the grantees of the Plan Shares (including two Directors). As of the Latest Practicable Date, Employee Shareholding Platforms held approximately 9.81% of our total issued Shares. The Employee Share Ownership Plan is not subject to the provisions of Chapter 17 of the Listing Rules as the Employee Share Ownership Plan does not involve the grant of options by our Company to subscribe for new Shares or award of Shares upon [REDACTED].

(a) Purpose

The purpose of the Employee Share Ownership Plan is to attract and retain talents for our Group, and to foster shared interests between our Shareholders and our employees, thereby furthering our Company’s focus on long-term development.

(b) Eligible participants

Persons eligible to participate in the Employee Share Ownership Plan are employees who hold important roles in our Group, and any other person whom the administrator of the Employee Share Ownership Plan considers appropriate.

(c) Vesting

The Plan Shares granted will vest in the following manner:

- i. as to 20% on the later of the first anniversary of the [REDACTED] and March 31, 2027;
- ii. as to 20% on the later of the first anniversary of the [REDACTED] and March 31, 2028;
- iii. as to 20% on the later of the first anniversary of the [REDACTED] and March 31, 2029;
- iv. as to 20% on the later of the first anniversary of the [REDACTED] and March 31, 2030; and
- v. as to 20% on the later of the first anniversary of the [REDACTED] and March 31, 2031.

In the event that the corresponding employment contract of a grantee is terminated prior to the vesting of the Plan Shares, such Plan Shares may be repurchased by the general partner or other grantees designated by the corresponding Employee Shareholding Platform at the original grant price at the direction of the administrator or continue to be held at the direction of the administrator.

(d) Disposal of the Plan Shares

Upon the vesting of the Plan Shares, any exit from, or reduction of, a grantee’s Plan Shares shall be effected through the disposal by the corresponding Employee Shareholding Platform of the Shares held by it. The proceeds from such disposal shall be distributed to the relevant grantee after deduction of applicable taxes and expenses, including operating expenses.

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E. OTHER INFORMATION

1. Estate Duty

Our Directors have been advised that no material liability for estate duty is likely to be imposed on our Company or our subsidiaries.

2. Litigation

To the knowledge of our Directors, no member of our Group has significant litigation or claims pending or threatened against any member of our Group.

3. Sole Sponsor

The Sole Sponsor has made an [REDACTED] on our behalf to the [REDACTED] for the [REDACTED] of, and [REDACTED] in, our H Shares in issue, our H Shares to be [REDACTED] pursuant to the [REDACTED] (including any H Shares which may fall to be [REDACTED] pursuant to the exercise of the [REDACTED]). All necessary arrangements have been made to enable the [REDACTED] to be admitted into [REDACTED].

Pursuant to the engagement letter entered into between the Company and the Sole Sponsor, we have agreed to pay the Sole Sponsor a fee of US\$900,000 to act as the sponsor of our Company in connection with the proposed [REDACTED] on the [REDACTED], which has yet to be paid in full to the Sole Sponsor as of the Latest Practicable Date.

CITIC Securities (Hong Kong) Limited satisfies the independence criteria applicable to sponsors set out in Rule 3A.07 of the Listing Rules. Please refer to “[REDACTED] — [REDACTED].”

4. Qualifications of Experts

The qualifications of the experts who have given opinions or advice in this Document are as follows:

Name	Qualification
CITIC Securities (Hong Kong) Limited	A corporation licensed to conduct Type 4 (advising on securities) and Type 6 (advising on corporate finance) of the regulated activities as defined under the SFO
PricewaterhouseCoopers	Certified Public Accountants under Professional Accountants Ordinance (Chapter 50 of the Laws of Hong Kong) Registered Public Interest Entity Auditor under Accounting and Financial Reporting Council Ordinance (Chapter 588 of the Laws of Hong Kong)
King & Wood	Legal advisor as to PRC law
King & Wood	Legal advisor as to PRC intellectual property law
Tsai, Lee & Chen	Legal advisor as to U.S. intellectual property law

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<u>Name</u>	<u>Qualification</u>
Lin & Partners	Legal advisor as to the Chinese Taiwan laws
Hogan Lovells International LLP	Legal advisor as to International sanctions, U.S. export controls, tariff laws and the Outbound Investment Rule
Frost & Sullivan (Beijing) Inc., Shanghai Branch Co.	Independent industry consultant
Cushman & Wakefield Limited .	Independent property valuer
KPMG Advisory (China) Limited Shenzhen Branch . . .	Transfer pricing consultant

Each of the experts named above has given and has not withdrawn its consent to the issue of this Document with the inclusion of its report, letter, and/or legal opinion (as the case may be) and references to its name included in the form and context in which it respectively appears.

As of the Latest Practicable Date, none of the experts named above has any shareholding interest in our Company or any of our subsidiaries or the right (whether legally enforceable or not) to subscribe for or to nominate persons to subscribe for securities in any member of our Group.

[REDACTED]

7. Compliance Advisor

Our Company has appointed Altus Capital Limited as its Compliance Advisor in compliance with Rule 3A.19 of the Listing Rules.

8. Preliminary Expenses

Our Company did not incur material preliminary expenses for the purpose of the Listing Rules.

9. No Material Adverse Change

Our Directors confirm that, as of the date of this Document, there has been no material change in our financial or financial position since March 31, 2026.

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10. Promoters

The promoters of our Company comprised all of the then shareholders of our Company, as of May 18, 2026 before our conversion into a joint stock limited liability company. Save as disclosed in this Document, within the two years immediately preceding the date of this Document, no cash, securities or benefit has been paid, allotted or given, or is proposed to be paid, allotted or given to the promoters named above in connection with the [REDACTED] or the related transactions described in this Document.

11. Taxation of Holders of H Shares

Hong Kong stamp duty, currently charged at the ad valorem rate of 0.10% on the higher of the consideration for or the market value of the H Shares, will be payable by the purchaser on every purchase and by the seller on every sale of any Hong Kong securities, including H Shares (in other words, a total of 0.20% is currently payable on a typical sale and purchase transaction involving H Shares). In addition, a fixed stamp duty of HK\$5.00 is currently payable on any instrument of transfer of H Shares. Where one of the parties is a resident outside Hong Kong and does not pay the ad valorem duty due by it, the duty not paid will be assessed on the instrument of transfer (if any) and will be payable by the transferee. If no stamp duty is paid on or before the due date, a penalty of up to 10 times the duty payable may be imposed.

12. Miscellaneous

Save as disclosed in this Document:

- (a) within the two years preceding the date of this Document: (i) we have not issued nor agreed to issue any share or loan capital fully or partly paid either for cash or for a consideration other than cash; (ii) no commissions, discounts, brokerage fees or other special terms have been granted in connection with the issue or sale of any shares of our Company; and (iii) no commission has been paid or is payable for subscription, agreeing to subscribe, procuring subscription or agreeing to procure subscription for any share in or debentures of our Company;
- (b) no share or loan capital of our Company is under option or is agreed conditionally or unconditionally to be put under option;
- (c) we have not issued nor agreed to issue any founder shares, management shares or deferred shares;
- (d) there are no contracts for hire or hire purchase of plant to or by us for a period of over one year which are substantial in relation to our business;
- (e) there are no arrangements under which future dividends are waived or agreed to be waived;
- (f) there are no procedures for the exercise of any right of pre-emption or transferability of subscription rights;
- (g) there have been no interruptions in our business which may have or have had a significant effect on our financial position in the last 12 months;
- (h) there are no restrictions affecting the remittance of profits or repatriation of capital by us into Hong Kong from outside Hong Kong;

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- (i) no part of the equity or debt securities of our Company, if any, is currently [REDACTED] on or [REDACTED] in on any stock exchange or trading system, and no such [REDACTED] or [REDACTED] on any stock exchange [REDACTED] is currently being or agreed to be sought;
- (j) our Company has no outstanding convertible debt securities or debentures; and
- (k) our Company is a joint stock company with limited liability and is subject to the PRC Company Law.